

Changed on e-puck PCB

e-puck

- suppressed central pad of mma7260 chip (stress problem on package making Z axis unusable for 20% production)
- clean routing around ball grid lmx9820
- changed micro to SPM0208HD5 model
- changed some routing under +Batt contact
- make pin-hole (TCRT1000 sensors) hole bigger
- footprint BSE connector changed
- changed package type of dspic30f6014A from PF to PT (from 14x14mm to 12x12mm)
- changed capacitor value BT clock -> 10p
- some little routing changes

e-jumper

- suppressed hole under tsop36 (not necessary)
- Selector less close to border
- footprint BTE connector
- changed footprint loudspeaker